

#3 3-7-02  
501.33873VC4

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: KAWAGOE, et al.  
Filed: December 14, 2001  
For: PROCESS FOR MANUFACTURING A  
SEMICONDUCTOR WAFER, A SEMICONDUCTOR  
WAFER, PROCESS FOR MANUFACTURING A  
SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE,  
AND SEMICONDUCTOR INTEGRATED CIRCUIT  
DEVICE

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents  
Washington, D.C. 20231

December 14, 2001

Sir:

Please amend the above-identified application, prior to examination  
thereof, as follows:

IN THE SPECIFICATION

Page 1, after the title and prior to the heading "BACKGROUND OF THE  
INVENTION", please insert the following:

A/ --This application is a Divisional application of application Serial No.  
09/513,349, filed February 25, 2000, which is a Continuation application of  
application Serial No. 08/934,774, filed September 22, 1997, now U.S. Patent

Conch  
AI  
No. 6,043,114, which is a Divisional application of application Serial No.

08/508,483, filed July 28, 1995.--

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11/11/95